

IN THE CLAIMS:

Please cancel any claims presently remaining in the Application and add the following new claims:

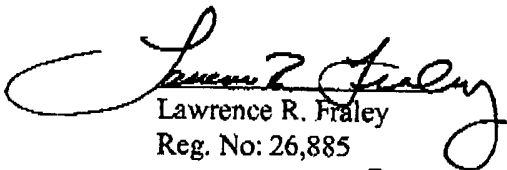
- 1 -13. A substrate for the attachment of a ball grid array electronic package thereto by means of
2 solder balls and solder paste wherein connection is made between a contact on the ball
3 grid array electronic package and a solder ball by means of a first joining medium and
4 between said solder ball and a contact arranged on the substrate by means of a second
5 joining medium and wherein the contact arranged on the substrate is substantially
6 quadrilateral in shape.
- 1 14. A substrate as claimed in claim 13 wherein the contact arranged on the substrate is
2 substantially square in shape.
- 1 15. A substrate as claimed in claim 13 wherein the joining medium is solder paste.
- 1 16. A substrate as claimed in claim 13 wherein said solder ball has an initial, substantially
2 round shape prior to making said connections.--

REMARKS

Entry is urged for the reasons stated above.

Respectfully submitted,

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